

MPSA92, MPSA93

High Voltage Transistors

PNP Silicon

Features

- Pb-Free Packages are Available*

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector–Emitter Voltage MPSA93 MPSA92	V_{CEO}	–200 –300	Vdc
Collector–Base Voltage MPSA93 MPSA92	V_{CBO}	–200 –300	Vdc
Emitter–Base Voltage	V_{EBO}	–5.0	Vdc
Collector Current – Continuous	I_C	–500	mAdc
Total Device Dissipation @ $T_A = 25^\circ\text{C}$ Derate above 25°C	P_D	625 5.0	mW mW/ $^\circ\text{C}$
Total Device Dissipation @ $T_C = 25^\circ\text{C}$ Derate above 25°C	P_D	1.5 12	W mW/ $^\circ\text{C}$
Operating and Storage Junction Temperature Range	T_J, T_{stg}	–55 to +150	$^\circ\text{C}$

THERMAL CHARACTERISTICS

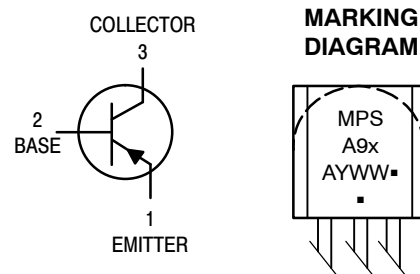
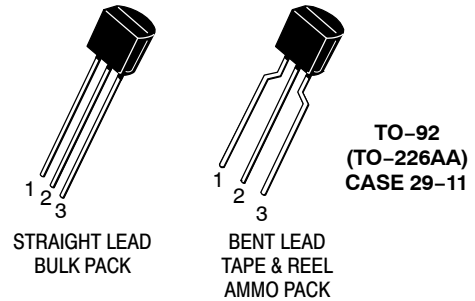
Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction–to–Ambient	$R_{\theta JA}$	200	$^\circ\text{C}/\text{W}$
Thermal Resistance, Junction–to–Case	$R_{\theta JC}$	83.3	$^\circ\text{C}/\text{W}$

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.



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x = 2 or 3
A = Assembly Location
Y = Year
WW = Work Week
▪ = Pb-Free Package
(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 3 of this data sheet.

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Characteristic		Symbol	Min	Max	Unit
OFF CHARACTERISTICS					
Collector–Emitter Breakdown Voltage (Note 1) ($I_C = -1.0\text{ mA}$, $I_B = 0$)	MPSA92 MPSA93	$V_{(BR)CEO}$	-300 -200	– –	Vdc
Collector–Base Breakdown Voltage ($I_C = -100\text{ }\mu\text{A}$, $I_E = 0$)	MPSA92 MPSA93	$V_{(BR)CBO}$	-300 -200	– –	Vdc
Emitter–Base Breakdown Voltage ($I_E = -100\text{ }\mu\text{A}$, $I_C = 0$)		$V_{(BR)EBO}$	-5.0	–	Vdc
Collector Cutoff Current ($V_{CB} = -200\text{ Vdc}$, $I_E = 0$) ($V_{CB} = -160\text{ Vdc}$, $I_E = 0$)	MPSA92 MPSA93	I_{CBO}	– –	-0.25 -0.25	μA
Emitter Cutoff Current ($V_{EB} = -3.0\text{ Vdc}$, $I_C = 0$)		I_{EBO}	–	-0.1	μA
ON CHARACTERISTICS (Note 1)					
DC Current Gain ($I_C = -1.0\text{ mA}$, $V_{CE} = -10\text{ Vdc}$) ($I_C = -10\text{ mA}$, $V_{CE} = -10\text{ Vdc}$) ($I_C = -30\text{ mA}$, $V_{CE} = -10\text{ Vdc}$)	All Types All Types MPSA92 MPSA93	h_{FE}	25 40 25 25	– – – –	–
Collector–Emitter Saturation Voltage ($I_C = -20\text{ mA}$, $I_B = -2.0\text{ mA}$)	MPSA92 MPSA93	$V_{CE(sat)}$	– –	-0.5 -0.4	Vdc
Base–Emitter Saturation Voltage ($I_C = -20\text{ mA}$, $I_B = -2.0\text{ mA}$)		$V_{BE(sat)}$	–	-0.9	Vdc
SMALL–SIGNAL CHARACTERISTICS					
Current–Gain – Bandwidth Product ($I_C = -10\text{ mA}$, $V_{CE} = -20\text{ Vdc}$, $f = 100\text{ MHz}$)		f_T	50	–	MHz
Collector–Base Capacitance ($V_{CB} = -20\text{ Vdc}$, $I_E = 0$, $f = 1.0\text{ MHz}$)	MPSA92 MPSA93	C_{cb}	– –	6.0 8.0	pF

1. Pulse Test: Pulse Width $\leq 300\text{ }\mu\text{s}$, Duty Cycle $\leq 2\%$.

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ORDERING INFORMATION

Device	Package	Shipping†
MPSA92G	TO-92 (Pb-Free)	5000 Units / Box
MPSA92RL1G	TO-92 (Pb-Free)	2000 / Tape & Reel
MPSA92RLRA	TO-92	2000 / Tape & Reel
MPSA92RLRAG	TO-92 (Pb-Free)	2000 / Tape & Reel
MPSA92RLRMG	TO-92 (Pb-Free)	2000 / Ammo Pack
MPSA92RLRPG	TO-92 (Pb-Free)	2000 / Ammo Pack
MPSA92ZL1G	TO-92 (Pb-Free)	2000 / Ammo Pack
MPSA93G	TO-92 (Pb-Free)	5000 Units / Box
MPSA93RLRMG	TO-92 (Pb-Free)	2000 / Ammo Pack

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

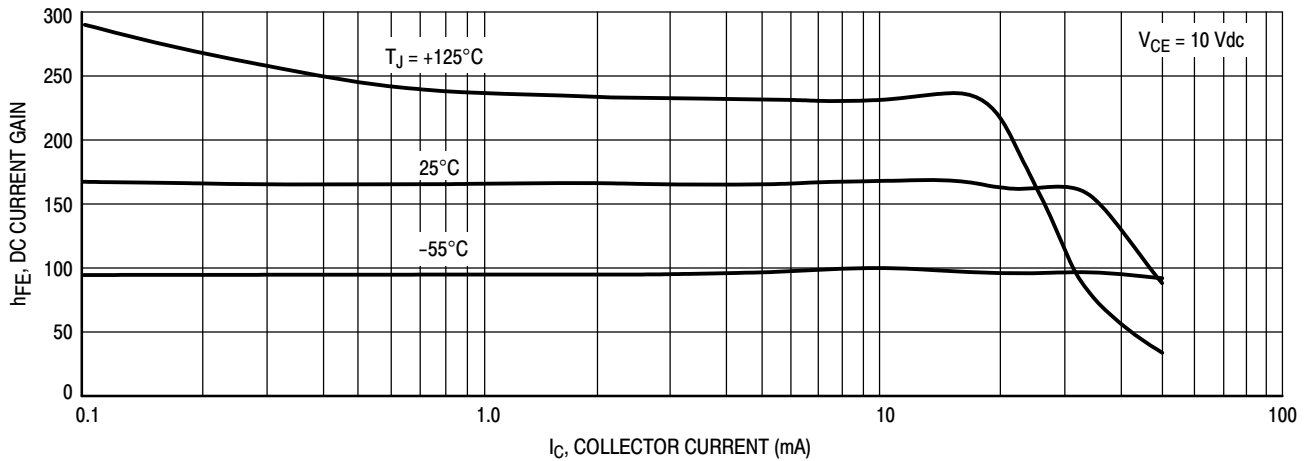


Figure 1. DC Current Gain

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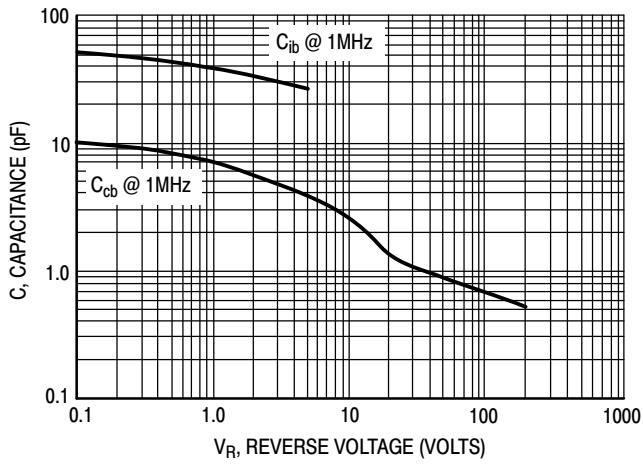


Figure 2. Capacitance

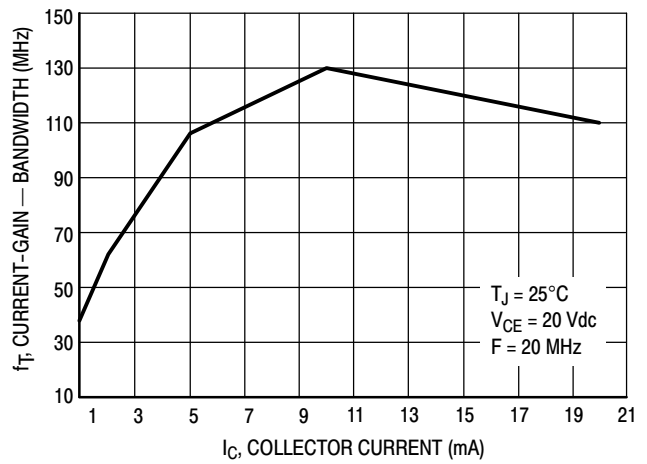


Figure 3. Current-Gain - Bandwidth

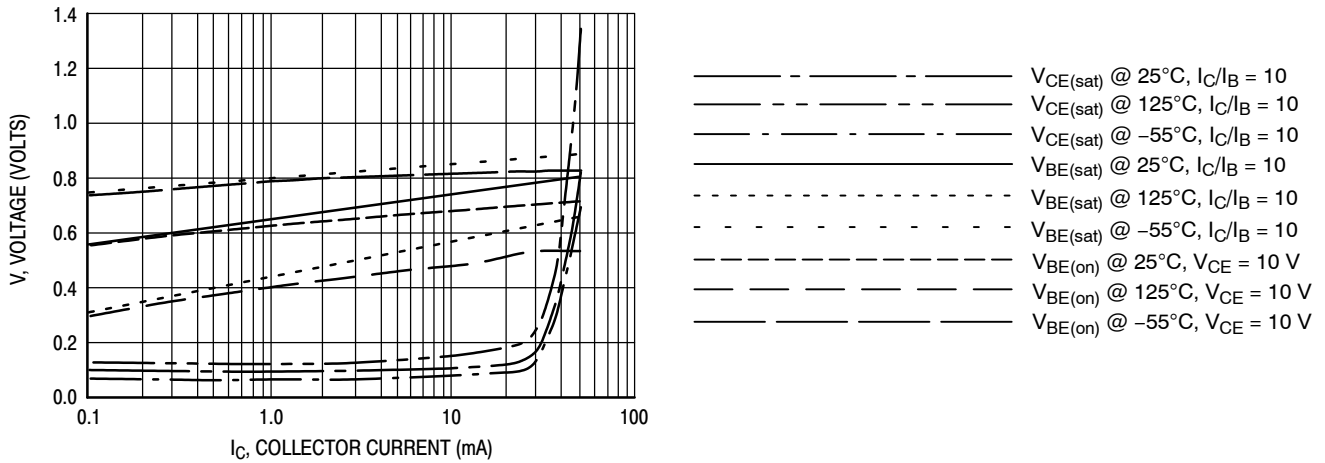


Figure 4. "ON" Voltages

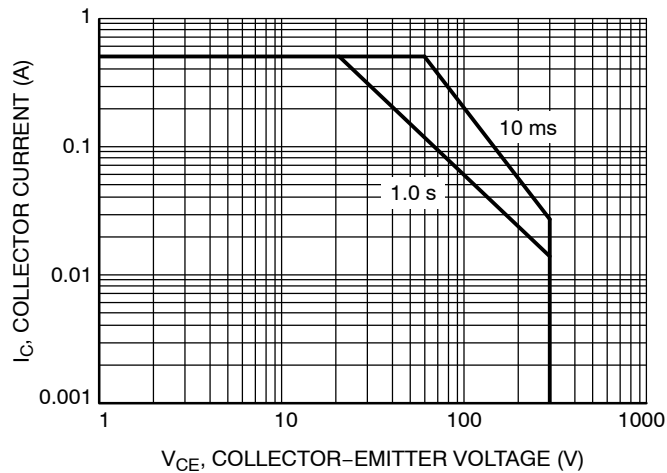
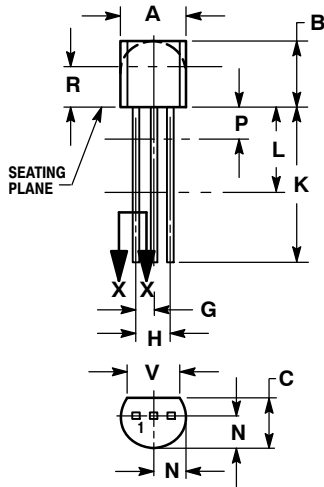


Figure 5. Safe Operating Area

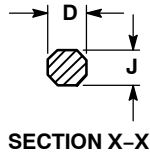
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PACKAGE DIMENSIONS

TO-92 (TO-226) CASE 029-11 ISSUE AM



STRAIGHT LEAD
BULK PACK



SECTION X-X

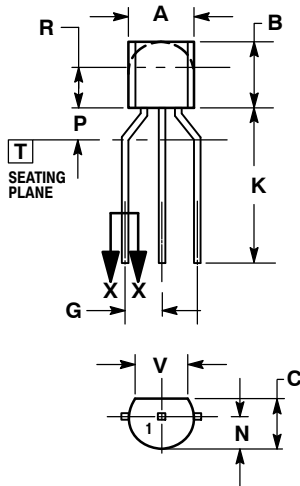
NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. CONTOUR OF PACKAGE BEYOND DIMENSION R IS UNCONTROLLED.
4. LEAD DIMENSION IS UNCONTROLLED IN P AND BEYOND DIMENSION K MINIMUM.

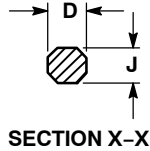
DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.175	0.205	4.45	5.20
B	0.170	0.210	4.32	5.33
C	0.125	0.165	3.18	4.19
D	0.016	0.021	0.407	0.533
G	0.045	0.055	1.15	1.39
H	0.095	0.105	2.42	2.66
J	0.015	0.020	0.39	0.50
K	0.500	---	12.70	---
L	0.250	---	6.35	---
N	0.080	0.105	2.04	2.66
P	---	0.100	---	2.54
R	0.115	---	2.93	---
V	0.135	---	3.43	---

STYLE 14:

1. EMITTER
2. COLLECTOR
3. BASE



BENT LEAD
TAPE & REEL
AMMO PACK




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NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. CONTOUR OF PACKAGE BEYOND DIMENSION R IS UNCONTROLLED.
4. LEAD DIMENSION IS UNCONTROLLED IN P AND BEYOND DIMENSION K MINIMUM.

DIM	MILLIMETERS	
	MIN	MAX
A	4.45	5.20
B	4.32	5.33
C	3.18	4.19
D	0.40	0.54
G	2.40	2.80
J	0.39	0.50
K	12.70	---
N	2.04	2.66
P	1.50	4.00
R	2.93	---
V	3.43	---

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